AEC-Q101 Qualified

2.5V Drive Pch MOS FET RTQ035P02FHA

Structure

Silicon P-channel MOSFET

Features

- 1) Low On-resistance.($80m\Omega$ at 2.5V)
- 2) High Power Package.
- 3) High speed switching.
- 4) Low voltage drive.(2.5V)

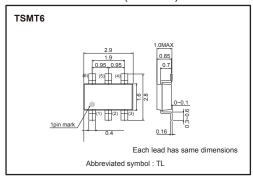
Applications

DC-DC converter

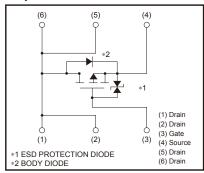
Packaging specifications

	Package	Taping
Туре	Code	TR
, ·	Basic ordering unit (pieces)	3000
RTQ035P02F	0	

●External dimensions (Unit : mm)



●Equivalent circuit



● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-source voltage		VDSS	-20	V
Gate-source voltage		Vgss	±12	V
Danie august	Continuous	ΙD	±3.5	A
Drain current	Pulsed	IDP *1	±17.5	A
Source current (Body diode)	Continuous	ls	-1	A
	Pulsed	Isp *1	-4	A
Total power dissipation		P _D *2	1.25	W
Channel temperature		Tch	150	°C
Range of Storage temperature		Tstg	-55 to +150	°C

^{∗1} Pw≤10μs, Duty cycle≤1%

*2 Modified on a defamile board

Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a) *	100	°C / W

^{*} Mounted on a ceramic board.

Rev.A

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	-	_	±10	μΑ	V _{GS} =±12V, V _{DS} =0V	
Drain-source breakdown voltage	V(BR)DSS	-20	_	-	V	I _D =-1mA, V _{GS} =0V	
Zero gate voltage drain current	IDSS	_	_	-1	μΑ	V _{DS} =-20V, V _{GS} =0V	
Gate threshold voltage	V _{GS(th)}	-0.7	_	-2.0	V	V _{DS} =-10V, I _D =-1mA	
		_	50	65	mΩ	I _D =-3.5A, V _G S=-4.5V	
Static drain-source on-state	RDS(on)	_	55	70	mΩ	I _D =-3.5A, V _G s=-4V	
resistance		_	80	100	mΩ	I _D =-1.75A, V _G s=-2.5V	
Foward transfer admittance	Yfs *	3.5	_	-	S	V _{DS} =-10V, I _D =-3.5A	
Input capacitance	Ciss	_	1200	-	pF	V _{DS} =-10V,V _{GS} =0V f=1MHz	
Output capacitance	Coss	_	200	-	pF		
Reverse transfer capacitance	Crss	_	130	-	pF		
Turn-on delay time	td(on) *	_	16	-	ns	1 – 24	
Rise time	tr *	_	40	-	ns	ID=-2A VDD=-15V VGS=-4.5V RL=7.5Ω RG=10Ω	
Turn-off delay time	td(off) *	_	55	-	ns		
Fall time	t _f *	_	30	-	ns		
Total gate charge	Qg	_	10.5	-	nC	V _{DD} ≒−15V V _{GS} =−4.5V I _D =−3.5A	
Gate-source charge	Qgs	_	2.0	_	nC		
Gate-drain charge	Qgd	_	3.5	-	nC		

^{*}PULSED

●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsp	_	-	-1.2	V	Is=-1A, Vgs=0V

Electrical characteristic curves Static Drain–Source On–State Resistance Res(on)[$m\Omega$] 1000 1000 Static Drain–Source On–State Resistance Res $[M\Omega]$ pulsed Drain Current : -Ib (A) 100 100 0.01 0.001 Gate-Source Voltage : -Vgs[V] Drain Current : -Ip[A] Fig.2 Static Drain-Source On-State Fig.1 Typical Transfer Characteristics Fig.3 Static Drain-Source On-State Resistance vs. Drain Current Resistance vs.Drain Current 1000 Static Drain–Source On–State Resistance Ros(on)[m\Omega] Static Drain–Source On–State Resistance $\mathsf{Ros}(\mathsf{on})[\mathsf{m}\Omega]$ -lpr[A] Reverse Drain Current: 100 0.01 10 L 0.1 Drain Current : -Io[A] Source-Drain Voltage : -Vsp[V] Drain Current : -ID[A] Fig.4 Static Drain-Source On-State Fig.5 Static Drain-Source On-State Fig.6 Reverse Drain Current vs. Source-Drain Voltage Resistancevs.Drain-Current Resistance vs. Drain-Current 10000 1000 Ta=25°C VDD=-15 VDD=-15V VGS=-4.5V RG=10Ω ID=-3.5V RG=10Ω Gate-Source Voltage: -Ves [V] Switching Time:t [ns] Capacitance : C [pF] 1000 100 100 10 L 0.01 Drain-Source Voltage : -Vps[V] $Drain\ Current: -I_D[A]$ Total Gate Charge : Qg[nC] Fig.7 Typical Capactitance

Fig.8 Switching Characteristics

vs.Drain-Source Voltage

Fig.9 Dynamic Input Characteristics

Measurement circuits

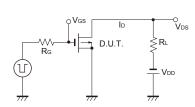


Fig.10 Switching Time Measurement Circuit

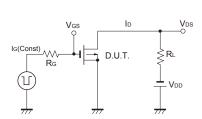


Fig.12 Gate Charge Measurement Circuit

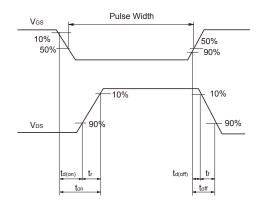


Fig.11 Switching Waveforms

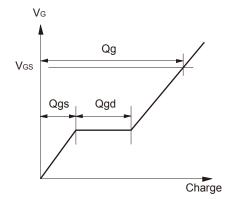


Fig.13 Gate Charge Waveforms

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JAPAN	USA	EU	CHINA	
CLASSⅢ	CLACCIII	CLASS II b	СГУССШ	
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSII	

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 - [h] Use of the Products in places subject to dew condensation
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 - [d] the Products are exposed to high Electrostatic
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- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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